Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **1A**
2. **1B**
3. **1Y**
4. **2A**
5. **2B**
6. **2Y**
7. **GND**
8. **3Y**
9. **3A**
10. **3B**
11. **4Y**
12. **4A**
13. **4B**
14. **Vcc**

**.047”**

**.043”**

**6 7 8**

**12**

**11**

**10**

**9**

**2**

**3**

**4**

**5**

**1 14 13**

**ACT08**

**MASK**

**REF**

**Top Material: Al**

**Backside Material: SiNi**

**Bond Pad Size: .004” X .004”**

**Backside Potential: Ground**

**Mask Ref: ACT08**

**APPROVED BY: DK DIE SIZE .043” X .047” DATE: 12/17/19**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54ACT08**

**DG 10.1.2**

#### Rev B, 7/19/02